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February 2014

ISL9R18120G2, ISL9R18120P2, ISL9R18120S3S

18 A, 1200 V, STEALTH™ Diode

Features

- Stealth Recovery t_{rr} = 300 ns (@ I_F = 18 A)
- Max Forward Voltage, V_F = 3.3 V (@ T_C = 25°C)
- 1200 V Reverse Voltage and High Reliability
- · Avalanche Energy Rated
- RoHS Compliant

Applications

- · Hard Switched PFC Boost Diode
- · UPS Free Wheeling Diode
- Motor Drive FWD
- SMPS FWD
- Snubber Diode

Description

The ISL9R18120G2, ISL9R18120P2, ISL9R18120S3S is a STEALTH $^{\rm TM}$ diode optimized for low loss performance in high frequency hard switched applications. The STEALTH $^{\rm TM}$ family exhibits low reverse recovery current (I $_{\rm RR}$) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low I $_{\rm RR}$ and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH $^{\rm TM}$ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

Package Symbol 2 LEAD TO-247 JEDEC TO-220AC JEDEC TO-263AB ANODE ANODE CATHODE CATHODE CATHODE (FLANGE) N/C ANODE CATHODE CATHODE (BOTTOM SIDE (FLANGE)

Device Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Rating	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
V _{RWM}	Working Peak Reverse Voltage	1200	V
V _R	DC Blocking Voltage	1200	V
I _{F(AV)}	Average Rectified Forward Current (T _C = 92°C)	18	Α
I _{FRM}	Repetitive Peak Surge Current (20kHz Square Wave)	36	Α
I _{FSM}	Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60Hz)	200	Α
P _D	Power Dissipation	125	W
E _{AVL}	Avalanche Energy (1A, 40mH)	20	mJ
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to 175	°C
T _L	Maximum Temperature for Soldering	300	°C
T_{PKG}	Leads at 0.063in (1.6mm) from Case for 10s	260	°C
	Package Body for 10s, See Application Note AN-7528		

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Mathod	Tape Width	Quantity
ISL9R18120G2	R18120G2	TO-247	Tube	N/A	30
ISL9R18120P2	R18120P2	TO-220AC	Tube	N/A	50
ISL9R18120S3S	R18120S3	TO-263AB	Reel	24mm	800

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test C	Conditions	Min	Тур	Max	Unit
Off State	Characteristics						
I _R	Instantaneous Reverse Current	V _R = 1200 V	T _C = 25°C	-	-	100	μA
			$T_{C} = 25^{\circ}C$ $T_{C} = 125^{\circ}C$	-	-	1.0	mA
On State	Characteristics						
V_{F}	Instantaneous Forward Voltage	I _F = 18 A	$T_C = 25^{\circ}C$	-	2.7	3.3	V
			T _C = 125°C	-	2.5	3.1	V
Dynamic	Characteristics						
СЈ	Junction Capacitance	$V_R = 10 \text{ V}, I_F = 0$	Α	-	69	-	pF
Switchin	ng Characteristics						
t _{rr}	Reverse Recovery Time	IF = 1 A, dIF/dt = 1	00 A/μs, V _R = 30 V	-	38	45	ns
		IF = 18 A, dIF/dt =	100 A/μs, V _R = 30 V	-	60	70	ns
t	Reverse Recovery Time	I⊏ = 18 A.		_	300	_	ns

	t _{rr}	Reverse Recovery Time	$I_F = 1 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$	-	38	45	ns
			$I_F = 18 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$	-	60	70	ns
	t _{rr}	Reverse Recovery Time	I _F = 18 A,	-	300	-	ns
	I _{rr}	Reverse Recovery Current	$dI_F/dt = 200 \text{ A/µs},$	- \	6.5	-	Α
Ī	Q _{rr}	Reverse Recovered Charge	$V_R = 780 \text{ V}, T_C = 25^{\circ}\text{C}$	-	950	-	nC
	t _{rr}	Reverse Recovery Time	I _F = 18 A,	-	400	-	ns
	S	Softness Factor (t _b /t _a)	dI _F /dt = 200 A/μs,	-	7.0	-	-
	I _{rr}	Reverse Recovery Current	$V_R = 780 \text{ V},$ $T_C = 125^{\circ}\text{C}$	-	8.0	-	Α
П	Q _{rr}	Reverse Recovered Charge	1C = 123 C	- /	2.0	-	μC
П	t _{rr}	Reverse Recovery Time	I _F = 18 A,	- /	235	-	ns
	S	Softness Factor (t _b /t _a)	$dI_F/dt = 1000 \text{ A/}\mu\text{s},$	-	5.2	-	-
	I _{rr}	Reverse Recovery Current	V _R = 780 V, T _C = 125°C	/-	22	-	Α
	Ο	Reverse Recovered Charge	1C - 123 C	_	21	_	uС

Thermal Characteristics

Maximum di/dt during tb

dl_M/dt

$R_{\theta JC}$	Thermal Resistance Junction to Case	TO-247, TO-220, TO-263	-	-	1.0	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-247	-	-	30	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-220, TO-263	-	-	62	°C/W

A/µs

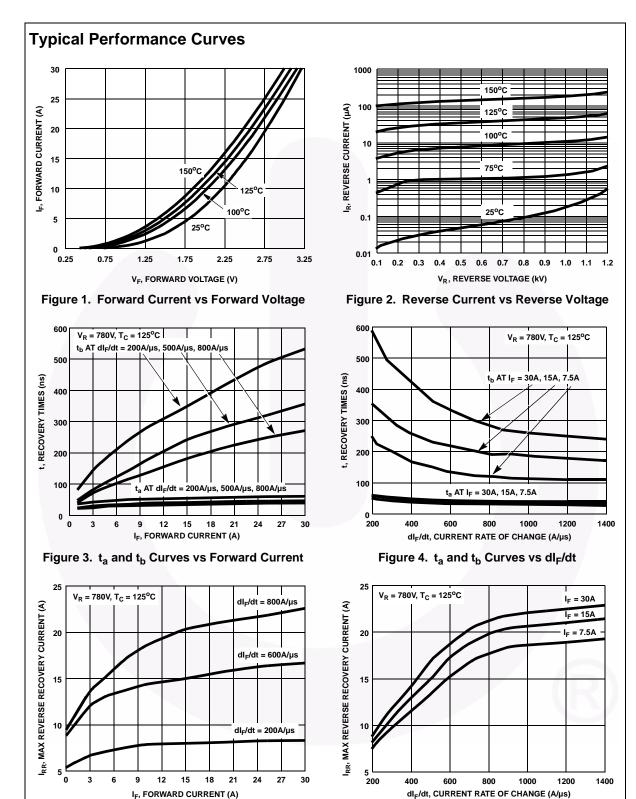
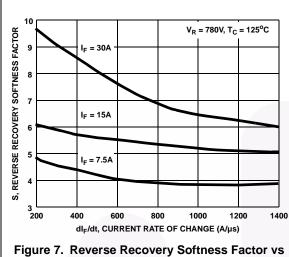


Figure 5. Maximum Reverse Recovery Current vs

Forward Current

Figure 6. Maximum Reverse Recovery Current vs

dl_F/dt



Typical Performance Curves (Continued)

dl_F/dt

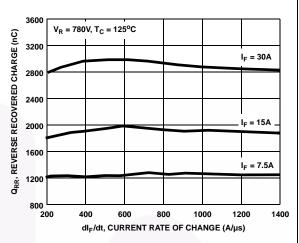


Figure 8. Reverse Recovered Charge vs dl_F/dt

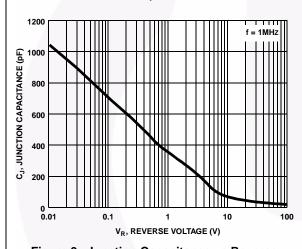


Figure 9. Junction Capacitance vs Reverse Voltage

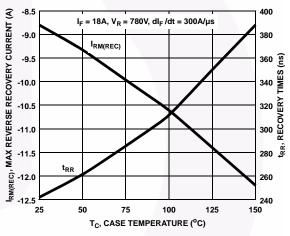


Figure 10. Reverse Recovery Current and Times vs Case Temperature

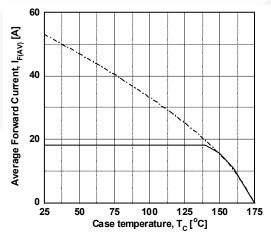


Figure 11. DC Current Derating Curve

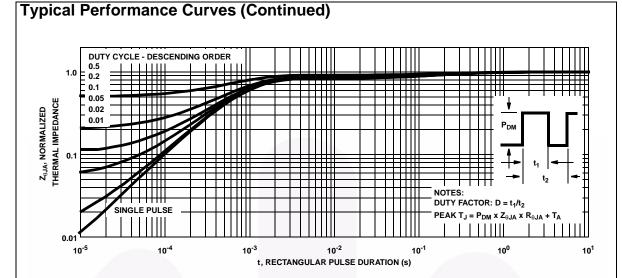


Figure 12. Normalized Maximum Transient Thermal Impedance

Test Circuit and Waveforms

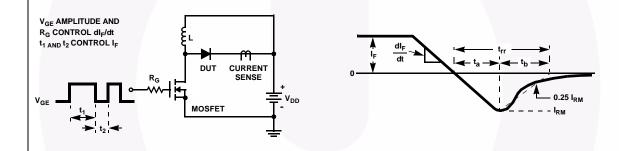


Figure 13. t_{rr} Test Circuit

Figure 14. t_{rr} Waveforms and Definitions

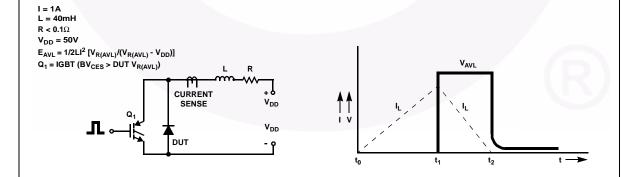


Figure 15. Avalanche Energy Test Circuit

Figure 16. Avalanche Current and Voltage Waveforms

Mechanical Dimensions

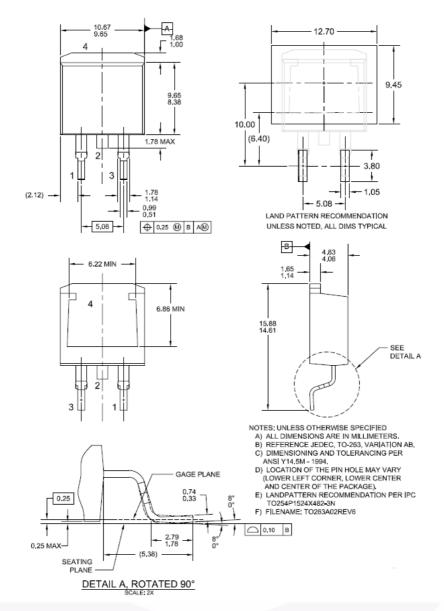


Figure 17. TO-263 2L (D2-PAK) - 2LD, TO263, SURFACE MOUNT

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Mechanical Dimensions

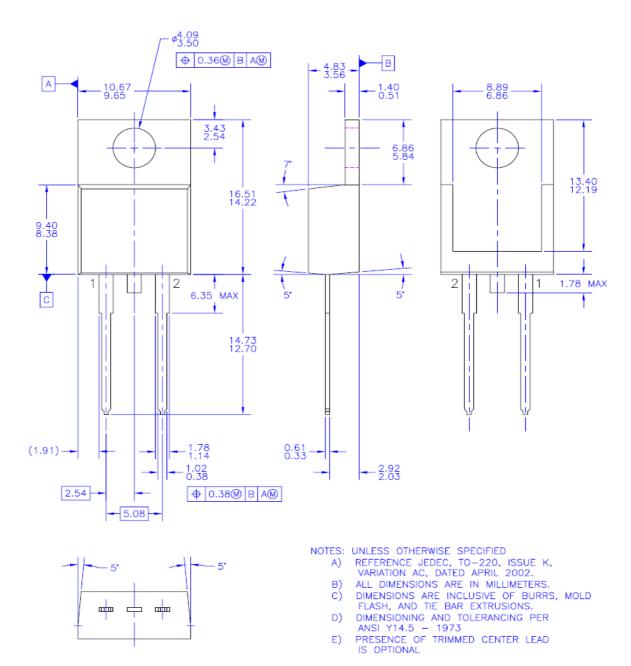


Figure 18. TO-220 2L - 2LD,TO220,JEDEC TO-220 VARIATION AC

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Mechanical Dimensions

TO247-2L

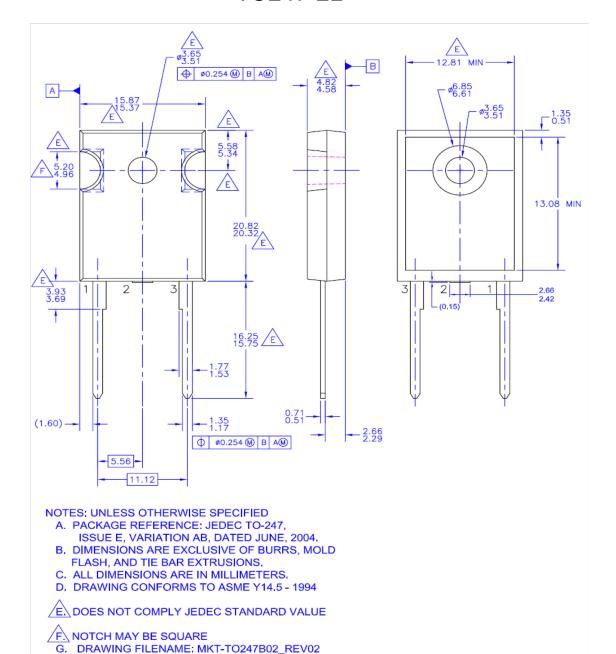


Figure 9. TO-247, Molded, 2LD, Jedec Option AB

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